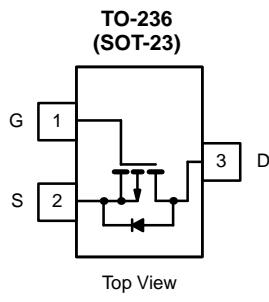




P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY

V _{DS} (V)	r _{D(on)} (Ω)	I _D (A)
-30	0.060 @ V _{GS} = -10 V	-4.1
	0.090 @ V _{GS} = -4.5 V	-3.0



Si2307

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±20	
Continuous Drain Current (T _J = 150°C) ^{a, b}	I _D	-4.1	A
Pulsed Drain Current	I _{DM}	-12	
Continuous Source Current (Diode Conduction) ^{a, b}	I _S	-1.25	
Power Dissipation ^{a, b}	P _D	1.25	W
		0.8	
Operating Junction and Storage Temperature Range	T _J , T _{Stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R _{thJA}		100	°C/W
		130		

Notes

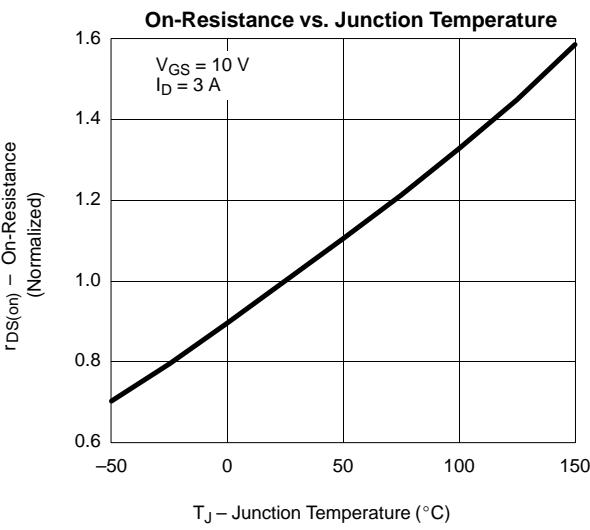
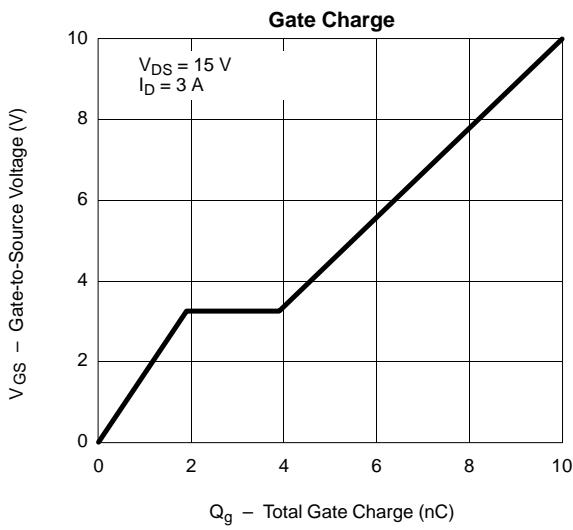
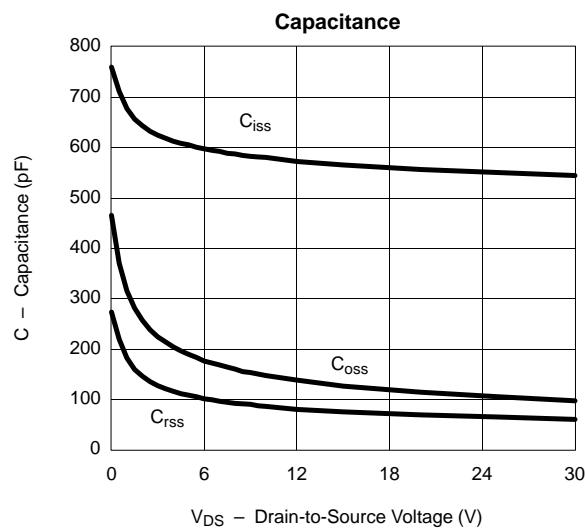
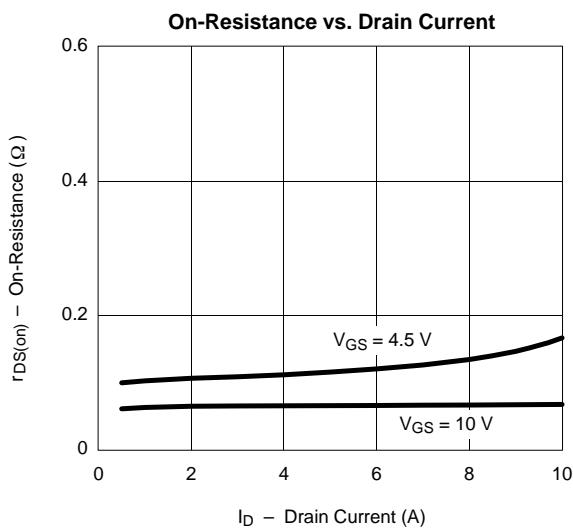
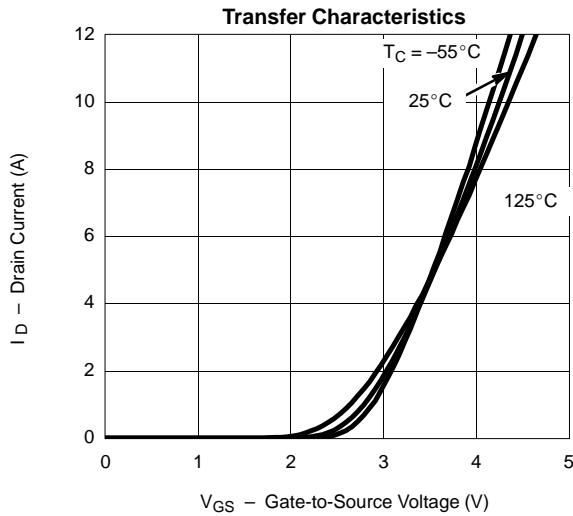
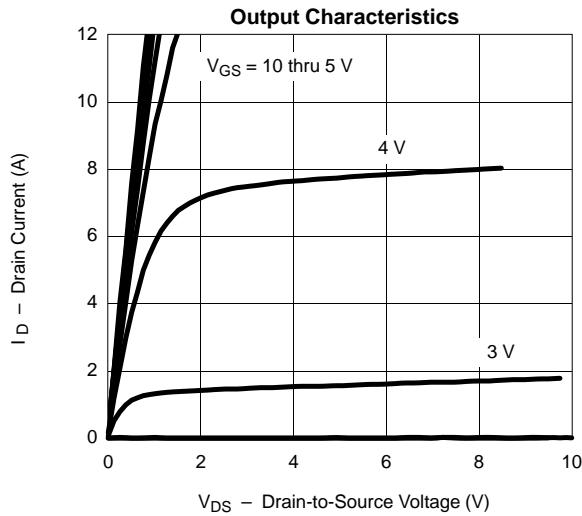
- a. Surface mounted on FR4 board.
- b. t ≤ 5 sec.

**SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)**

Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = -10 \mu\text{A}$	-30			V
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250 \mu\text{A}$	-0.8		3.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -24 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			-1	μA
On-State Drain Current ^a	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} \leq -5 \text{ V}, V_{\text{GS}} = -10 \text{ V}$	-6			A
Drain-Source On-Resistance ^a	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10 \text{ V}, I_D = -4.1 \text{ A}$			0.060	Ω
		$V_{\text{GS}} = -4.5 \text{ V}, I_D = -3.0 \text{ A}$			0.090	
Forward Transconductance ^a	g_{fs}	$V_{\text{DS}} = -10 \text{ V}, I_D = -3 \text{ A}$		4.5		S
Diode Forward Voltage	V_{SD}	$I_S = -1.25 \text{ A}, V_{\text{GS}} = 0 \text{ V}$			-1.0	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{\text{DS}} = -15 \text{ V}, V_{\text{GS}} = -10 \text{ V}$ $I_D \approx -3 \text{ A}$		10	15	nC
Gate-Source Charge	Q_{gs}			1.9		
Gate-Drain Charge	Q_{gd}			2		
Input Capacitance	C_{iss}	$V_{\text{DS}} = -15 \text{ V}, V_{\text{GS}} = 0, f = 1 \text{ MHz}$		565		pF
Output Capacitance	C_{oss}			126		
Reverse Transfer Capacitance	C_{rss}			75		
Switching^b						
Turn-On Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -15 \text{ V}, R_L = 15 \Omega$ $I_D \approx -1.0 \text{ A}, V_{\text{GEN}} = -10 \text{ V}$ $R_G = 6 \Omega$		10	20	ns
	t_r			9	20	
Turn-Off Time	$t_{\text{d}(\text{off})}$			27	50	
	t_f			7	16	

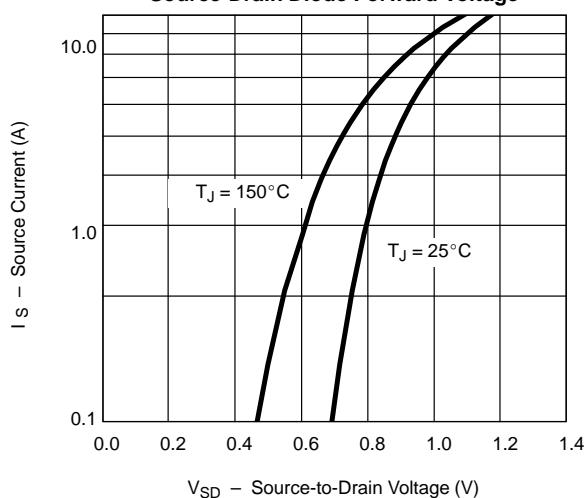
Notes

- a. Pulse test: $PW \leq 300 \mu\text{s}$ duty cycle $\leq 2\%$.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

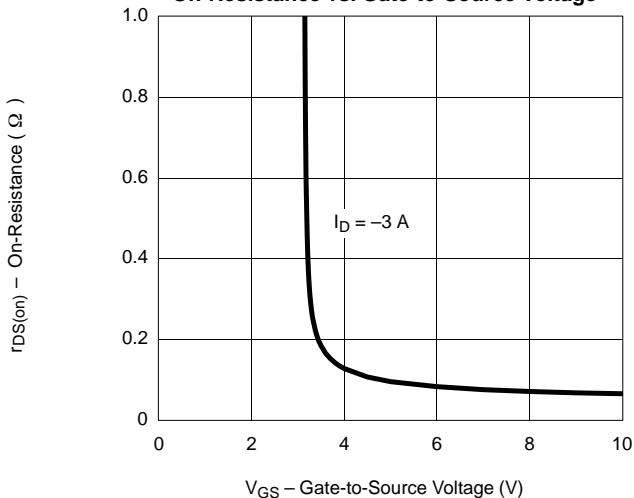
**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**

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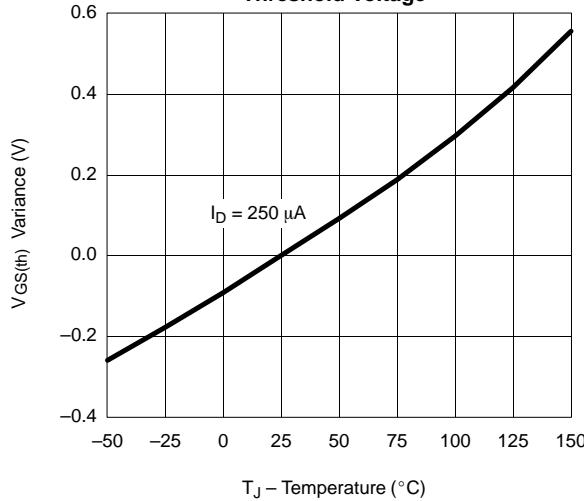
Source-Drain Diode Forward Voltage



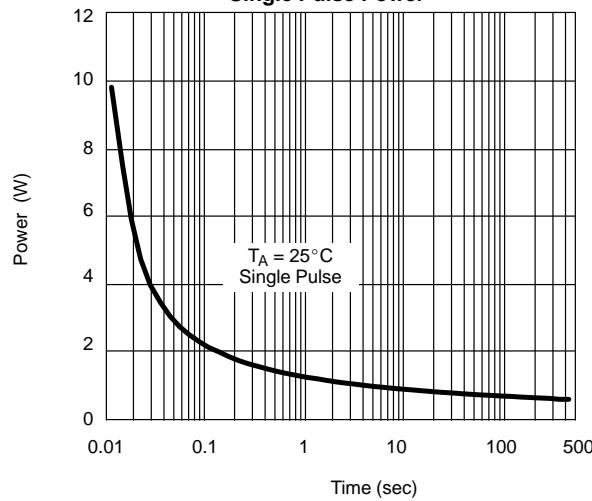
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power



Normalized Thermal Transient Impedance, Junction-to-Ambient

